Surface Mount Ultrafast Power Rectifiers

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (0.74 V Max @ 2.0 A, T_J = 150°C)
- SURS8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 95 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Ratings:
 - Machine Model = C (> 400 V)
 - Human Body Model = 3A (> 4 kV)



ON Semiconductor®

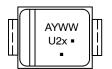
www.onsemi.com

ULTRAFAST RECTIFIERS 2 AMPERES, 50–100 VOLTS



SMB CASE 403A

MARKING DIAGRAM



A = Assembly Location*

′ = Year

WW = Work Week U2x = Device Code

x = A for MURS205T3G

= B for MURS210T3G

= Pb-Free Package

(Note: Microdot may be in either location)

* The Assembly Location Code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping [†]		
MURS205T3G	SMB (Pb-Free)	2,500 Tape & Reel		
SURS8205T3G	SMB (Pb-Free)	2,500 Tape & Reel		
MURS210T3G	SMB (Pb-Free)	2,500 Tape & Reel		
SURS8210T3G	SMB (Pb-Free)	2,500 Tape & Reel		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage MURA205T3G, SURS8205T3G MURA210T3G, SURS8210T3G	V _{RRM} V _{RWM} V _R	50 100	>
Average Rectified Forward Current @ $T_L = 150^{\circ}C$ @ $T_L = 125^{\circ}C$	I _{F(AV)}	1.0 2.0	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	50	Α
Operating Junction Temperature	T _J	-60 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

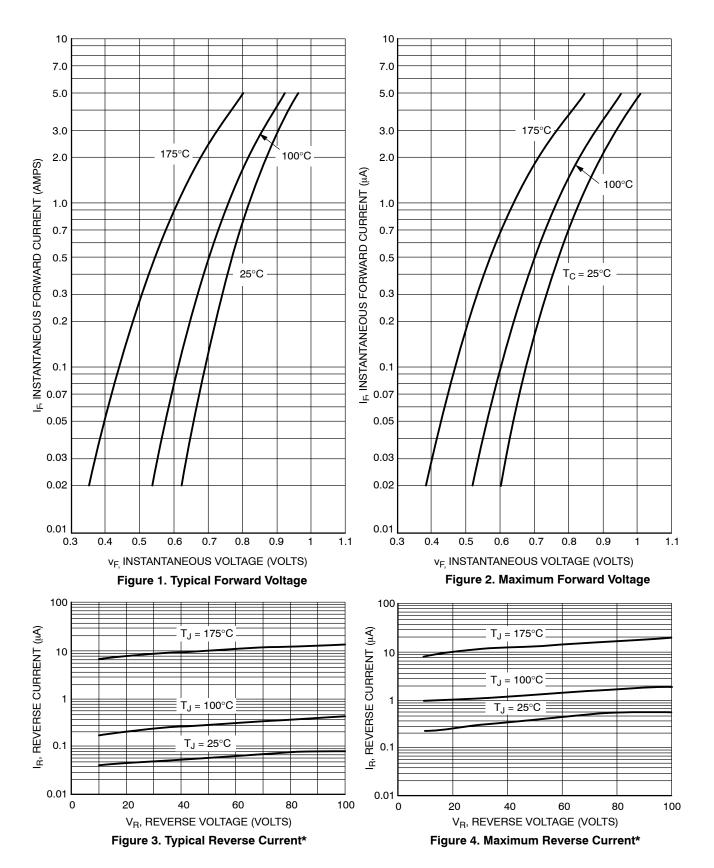
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Lead (T _L = 25°C)	$R_{ hetaJL}$	13	°C/W

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit	
Maximum Instantaneous Forward Voltage (Note 1) $(i_F = 2.0 \text{ A}, T_J = 25^{\circ}\text{C})$ $(i_F = 2.0 \text{ A}, T_J = 150^{\circ}\text{C})$	V _F	0.94 0.74	V	
Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_J = 25^{\circ}C$) (Rated dc Voltage, $T_J = 150^{\circ}C$)	İR	2.0 50	μΑ	
Maximum Reverse Recovery Time $ (i_F=1.0 \text{ A, di/dt}=50 \text{ A/}\mu\text{s}) $	t _{rr}	30 20	ns	
Maximum Forward Recovery Time (i _F = 1.0 A, di/dt = 100 A/μs, Rec. to 1.0 V)	t _{fr}	20	ns	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{1.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.



^{*} The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these same curves if applied V_R is sufficiently below rated V_R.

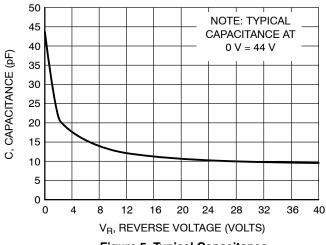


Figure 5. Typical Capacitance

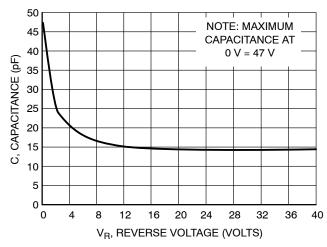


Figure 6. Maximum Capacitance

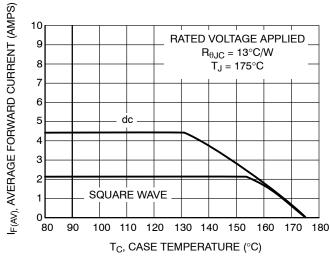


Figure 7. Current Derating, Case

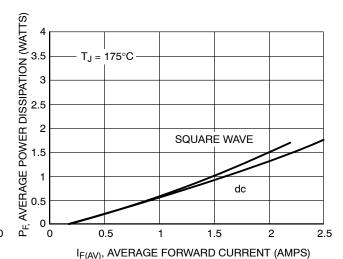
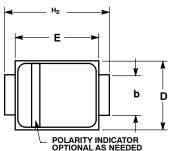
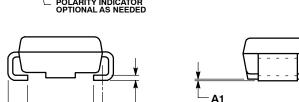


Figure 8. Power Dissipation

PACKAGE DIMENSIONS

SMB CASE 403A-03 **ISSUE J**

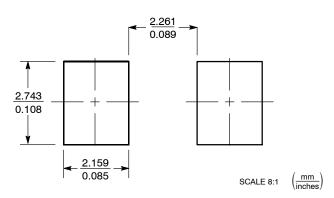




- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
С	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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